

**Amendment and Response**

Applicant: Andrew Harvey Barr et al.

Serial No.: 10/621,925

Filed: July 17, 2003

Docket No.: 200308576-1 (H300.213.101)

Title: ALTERNATING VOIDED AREAS OF ANTI-PADS

---

**IN THE SPECIFICATION**

Please replace the paragraph starting on page 3, line 6 with the following rewritten paragraph:

For reasons stated above and for other reasons presented in the present ~~specification~~specification, there is a need for a PCB that includes anti-pad designs associated with vias that will minimize capacitance, maximize board planarity, and minimize signal trace routing issues, thereby allowing high speed serial communications regardless of the environment or application.

Please replace the Abstract with the following rewritten Abstract:

A printed circuit board ~~comprises~~includes a first conductive plane and a second conductive plane substantially parallel to the first conductive plane. The printed circuit board ~~comprises~~includes a via signal barrel transecting the first and second conductive planes and a first anti-pad positioned between the first conductive plane and the via signal barrel. The first anti-pad has a first voided area. The printed circuit board ~~comprises~~includes a second anti-pad positioned between the second conductive plane and the via signal barrel. The second anti-pad has a second voided area. The first voided area does not completely overlap the second voided area.